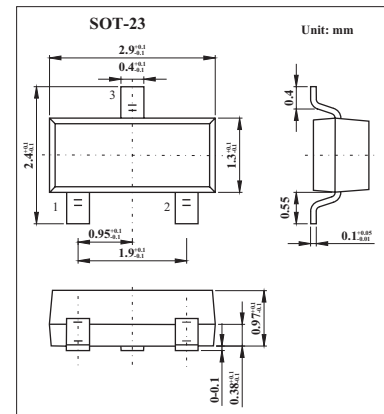
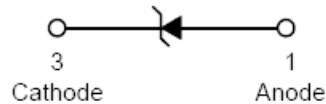


## 350mW Surface Mount Zener Diode MMBZ5251B

### ■ Features

- Planar Die Construction
- General Purpose, Medium Current
- Ideally Suited for Automated Assembly Processes



### ■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Forward Voltage @ $I_F = 10\text{mA}$	$V_F$	0.9	V
Power Dissipation *1	$P_d$	350	mW
Thermal Resistance, Junction to Ambient Air *1	$R_{\theta JA}$	357	$^\circ\text{C}/\text{W}$
Operating and Storage Temperature Range	$T_j, T_{STG}$	-65 to +150	$^\circ\text{C}$

\*1. Part mounted on FR-4 PC board with recommended pad layout

### ■ Electrical Characteristics @ $T_A=25^\circ\text{C}$ unless otherwise specified

Type Number	Zener Voltage Range *1				Maximum Zener Impedance *2		Maximum Reverse Leakage Current *1	
	$V_z @ I_{ZT}$			$I_{ZT}$	$Z_{ZT} @ I_{ZT}$	$Z_{ZK} @ I_{ZK} = 0.25\text{mA}$	$I_R$	@ $V_R$
	Nom (V)	Min (V)	Max (V)	mA	$\Omega$		$\mu\text{A}$	V
MMBZ5251B	22	20.9	23.1	5.6	29	600	0.1	17

\*1. Short duration test pulse used to minimize self-heating effect.

\*2.  $f = 1\text{KHz}$ .

### ■ Marking

Marking	KK1
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### MMBZ5251B

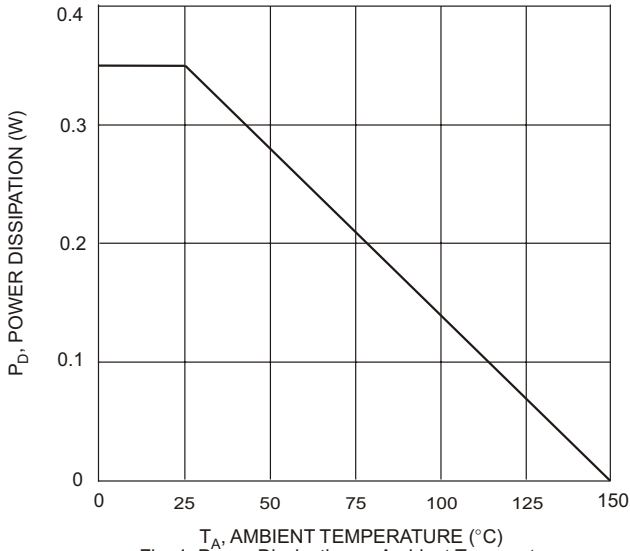


Fig. 1 Power Dissipation vs Ambient Temperature

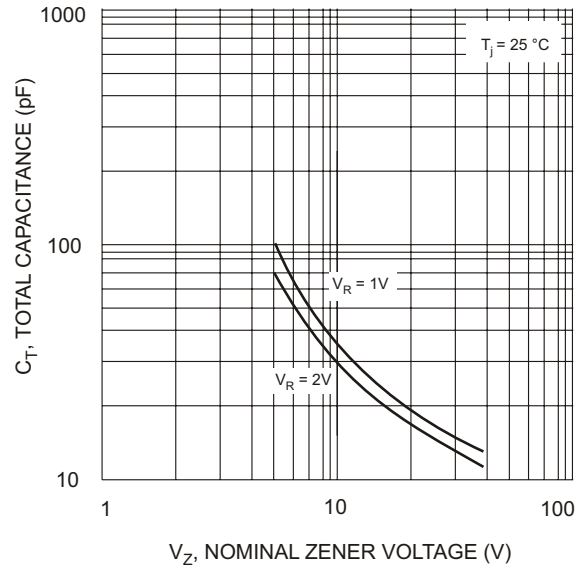


Fig. 2 Total Capacitance vs Nominal Zener Voltage

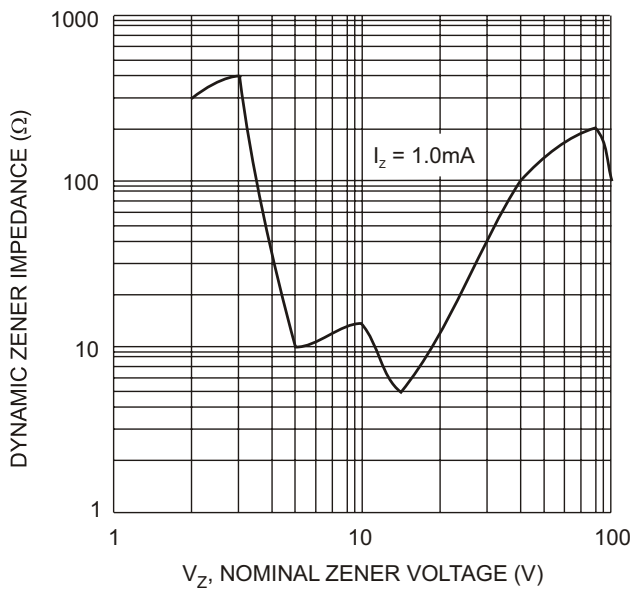


Fig. 3 Zener Voltage vs. Zener Impedence

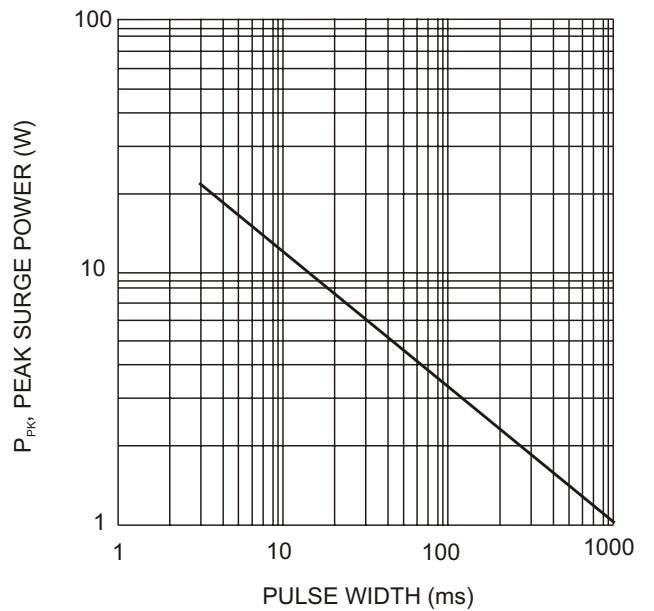


Fig. 4 Maximum Non-repetitive Surge Power

### MMBZ5251B

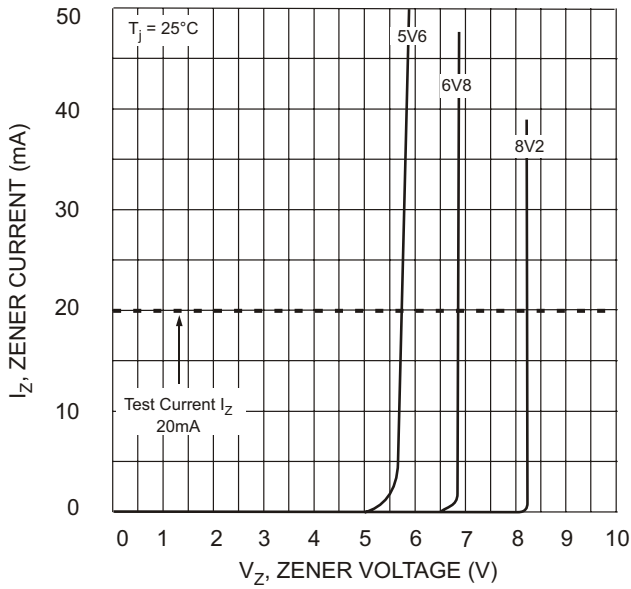


Fig. 5 Zener Breakdown Characteristics

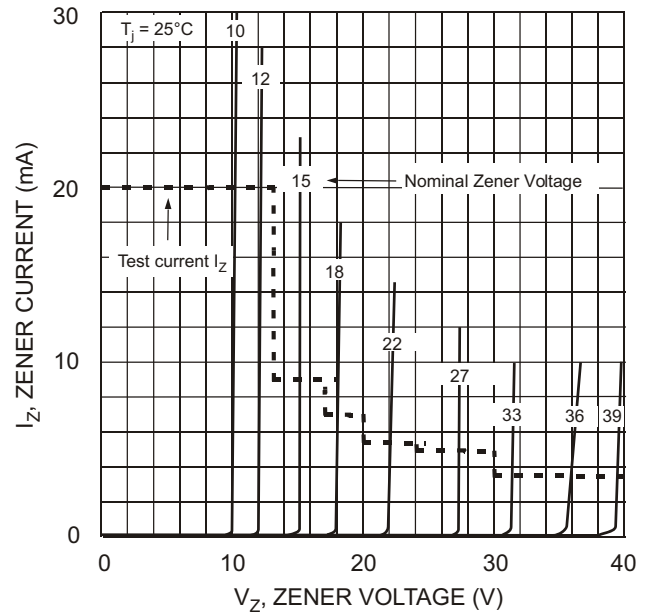


Fig. 6 Zener Breakdown Characteristics